

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER : 2001107008  
PUBLICATION DATE : 17-04-01

APPLICATION DATE : 22-09-00  
APPLICATION NUMBER : 2000288314

APPLICANT : QUESTECH SOLUTIONS PTE LTD;

INVENTOR : WAN TEIE;

INT.CL. : C09J163/00

TITLE : FLUXING ADHESIVE

ABSTRACT : PROBLEM TO BE SOLVED: To provide improved underfill adhesives having fluxing activity.

SOLUTION: An improved underfill adhesive capsulating agent having fluxing activity which is used in capsulating the soldered portion of the gap between electronic parts comprises an epoxy resin or a mixture of epoxy resins. The epoxy resin is cured with the use of an anhydride as the curing agent. An active fluxing agent is prepared by adding a hydroxyl-containing fluxing precursor compound to this capsulating agent composition to effect reaction with the anhydride curing agent under typical reflowing conditions. Use of this fluxing precursor substance improves reliability compared to the conventional fluxing agent which is used in the conventional non-reflowing underfill capsulating agent. An appropriate catalyst such as imidazole, an imidazole derivative, and a metal acetylacetonate is added to this capsulating agent at a concentration of bringing about good curing dynamics. In order to reprocess the cured capsulating agent, a thermoplastic plastic is selectively incorporated.

COPYRIGHT: (C)2001,JPO